

Serial No. 10/032,734

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Serial No.: 10/032,734

Filed: December 28, 2001

For: MULTI-CHIP MODULE SYSTEM
AND METHOD OF FABRICATION

Confirmation No.: 6382

Examiner: D. Graybill

Group Art Unit: 2827

Attorney Docket No.: 2269-2754.4US
(95-0742.04/US)

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CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

September 15, 2003
Date

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Debra Pfeil
Name (Type/Print)

AMENDMENT UNDER 37 C.F.R. § 1.116

Mail Stop AF
Commissioner for Patents
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Sir:

This amendment is in response to the Final Office Action of July 17, 2003, whose initial period of response is set to expire on October 17, 2003.